

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4106970

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ATSUSHI SADO	10/13/2016
CHIHARU HAYASHI	10/14/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIYO YUDEN CO., LTD.
<b>Street Address:</b>	16-20 UENO 6-CHOME
<b>City:</b>	TAITO-KU, TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	110-0005
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15276669
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(949)457-8297
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	949-457-8296
<b>Email:</b>	KAPAT@KAPATLAW.COM
<b>Correspondent Name:</b>	LAW OFFICE OF KATSUHIRO ARAI
<b>Address Line 1:</b>	22471 ASPAN STREET
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<b>ATTORNEY DOCKET NUMBER:</b>	T150018US
<b>NAME OF SUBMITTER:</b>	KATSUHIRO ARAI
<b>SIGNATURE:</b>	/katsuhiro arai/
<b>DATE SIGNED:</b>	10/20/2016
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 3</b>	
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**ASSIGNMENT COMBINED WITH  
DECLARATION FOR UTILITY/DESIGN PATENT APPLICATION (37 CFR 1.63(e))**

**WHEREAS**, as a below named inventor, I hereby declare under 37 C.F.R. 1.63 that:

I have invented certain new and useful work in

**COIL COMPONENT AND METHOD OF MANUFACTURING THE SAME**

for which a patent application in the United States (hereinafter "Application"):

☐ is attached hereto or concurrently filed herewith

OR

☒ was filed on [mm/dd/yyyy]

**09/26/2016**

as United States Application Number or PCT International Application Number

**15/276,669**

This declaration is directed to the Application;

The Application was made or authorized to be made by me;

I believe that I am the original or an original joint inventor of a claimed invention in the application;

I hereby acknowledge that any willful false statement made in this document is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both;

I also acknowledge that a person may not execute an oath or declaration for an application unless that person has reviewed and understands the contents of the application, including the claims, and is aware of the duty to disclose to the U.S. Patent and Trademark Office all information known to the person to be material to patentability as defined in 37 C.F.R. 1.56; and

I authorize practitioners associated with Customer Number **76993** to insert on this document the serial number, filing date, and any further identification that may be necessary or desirable by the U.S. Patent and Trademark Office;

**AND WHEREAS, TAIYO YUDEN CO., LTD.**, a Japanese corporation, with its principal place of business at (hereinafter "ASSIGNEE"), desires to acquire the entire right, title, and interest in and to said work and said Application;

**NOW, THEREFORE**, for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned inventor(s) (individual(s) hereinafter "ASSIGNOR") do/does hereby acknowledge that the ASSIGNOR has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under said work, and said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said work in any country or countries foreign to the United States, and all Letters Patent which may be granted for said work in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and the ASSIGNOR hereby authorizes and requests the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said work to said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

AND ASSIGNOR DOES HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of said Letters Patent before or after issuance; and

AND ASSIGNOR DOES HEREBY covenant and agree that the ASSIGNOR will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to the ASSIGNOR respecting said work, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said work in all countries.

IN TESTIMONY WHEREOF, the ASSIGNOR executes this assignment:

<b>NAME OF FIRST INVENTOR</b>	
First and Middle [if any] <b>Atsushi</b>	FAMILY NAME <b>SADO</b>
Inventor's Signature <i>Atsushi Sado</i>	Date <i>2016.10.13</i>
<b>NAME OF SECOND INVENTOR</b>	
First and Middle [if any] <b>Chiharu</b>	FAMILY NAME <b>HAYASHI</b>
Inventor's Signature	Date

**AND ASSIGNOR DOES HEREBY** sell, assign, transfer, and convey to said ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of said Letters Patent before or after issuance; and

**AND ASSIGNOR DOES HEREBY** covenant and agree that the ASSIGNOR will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to the ASSIGNOR respecting said work, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said work in all countries.

**IN TESTIMONY WHEREOF**, the ASSIGNOR executes this assignment:

<b>NAME OF FIRST INVENTOR</b>	
First and Middle [if any] <b>Atsushi</b>	FAMILY NAME <b>SADO</b>
Inventor's Signature	Date
<b>NAME OF SECOND INVENTOR</b>	
First and Middle [if any] <b>Chiharu</b>	FAMILY NAME <b>HAYASHI</b>
Inventor's Signature <i>Chiharu Hayashi</i>	Date <i>10/14/2016</i>